

BM-Slim2S

Ultra-slim FAP20 Standalone Authentication Module



BM-Slim2S is a FBI PIV and Mobile ID FAP20 certified fingerprint module that provides a number of industry-leading features under its sleek design. Featuring range-leading powerful 1.0GHz CPU, BM-Slim 2S provides high-speed extraction and matching of fingerprints within the scanner.

BM-Slim2S also supports true plug-n-play by featuring HID(human interface device) protocol. BM-Slim2S is a versatile identification solution for both public and civil ID applications.



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FEATURES

SPECIFICATIONS

¢0	 True plug-n-play operation HID(human interface device) protocol 	Sensor	Image Quality Standards	FBI PIV / FBI Mobile ID FAP20
			Live Finger Detection	0
			Sensor Type	Optical
	 Standalone operation 1.0GHz MIPS-base Xburst Core CPU On-device fingerprint extraction and matching O/S independent fingerprint scanner 		Resolution	500 ppi
			Gray Scale	256 level
			Platen Size (W x L mm)	16.5 x 21.0
			Sensing Area (W x H mm)	15.24 x 20.32
			Image Size (W x H pixels)	300 x 400
ð	 Enhanced Security On-device template encryption On-device template extraction 	н/w	Interface	USB 2.0 Hight Speed
			Operating Temperature(°C)	-10 ~ 55°C
			Operating humidity	0 ~ 90% RH
			Dimensions (W x L x Hmm)	IP65 (Sensor Surface)
<u>↓</u>	· World's slimmest FAP 20 optical sensor	s/w	Windows	OS/Platform Independent, Stand-alone Operation
			Linux	OS/Platform Independent, Stand-alone Operation
FBI	 FBI PIV/FIPS201 and FBI Mobile ID FAP20 certificates Image compression standard: WSQ 		Android Android 5.0 or later	OS/Platform Independent, Stand-alone Operation
			Image Format	RAW, BMP, WSQ, ISO 19794-4
			Template Type	Xperix, ISO19794-2, ANSI-378
Multi Dynamic Range	 Capturing high-quality fingerprint images even when the finger is dry & wet. Operates under direct sunlight up to 100,000 LUX 	Certification	CE	0
			FCC	0
			KC	0
			UL / CB	0
			IEC62471	0
	 Live Fingerprint Detection (LFD) Technology Distinguishes fake fingerprints made from various materials including clay, rubber, silicon, glue, paper, film and more 		WEEE	0
			WHQL	0

Automated power saving by smart sleep mode BM-Slim 2S now consumes up to95% less power than competitors



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